Communications and Computer Engineering II

FPGA Basis

Hiroki Nakahara Tokyo Institute of Technology

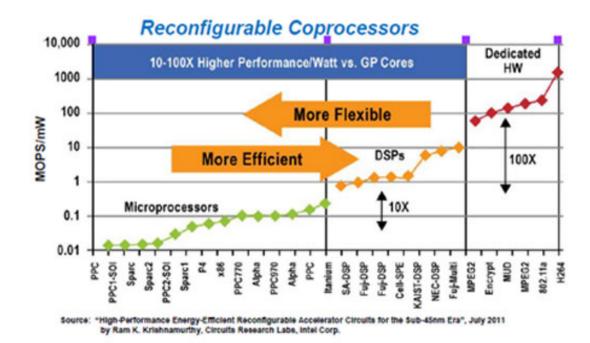
Outline

- What's FPGA?
 - Recent trends
- FPGA Architecture
- Standard FPGA Design
 - RTL (Register Transfer Level)
 - High-level synthesis (HLS)
 - System-level design
- Summary

1.1 FPGA

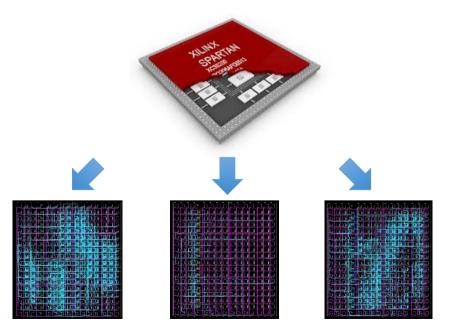
The Dilemma: Flexibility vs. Efficiency

- FPGAs often offer the best of both worlds replacing MPUs, DSPs, and dedicated ASSPs or ASICs
- Their on-the-fly reconfigurability helps them realize insystem logic functions that CPUs can't



FPGA

- Reconfigurable LSI or Programmable Hardware
- Programmable Logic Array and Programmable Interconnection
- Programmed by Reconfigurable Data

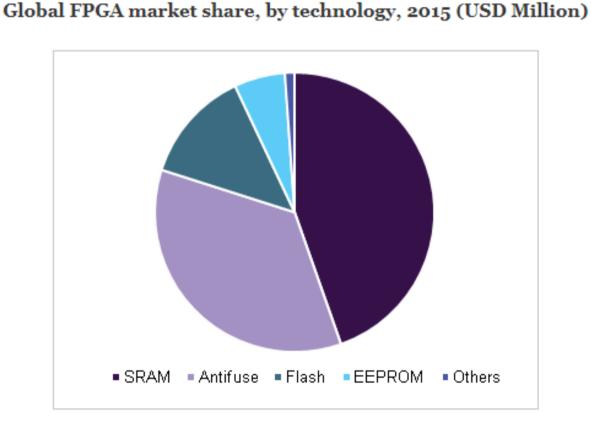


Pros. and Cons.

- Pros.
 - Short TAT(Turn-Around Time)
 - Small NRE (Non Recurrent Expense) Fee
 - Logic and Timing Design are required.
 - Full amount of IP (Intellectual Property)
- Cons.
 - Slow speed and Large Chip Area
 - High cost for volume manufacturing

Product Type Segments

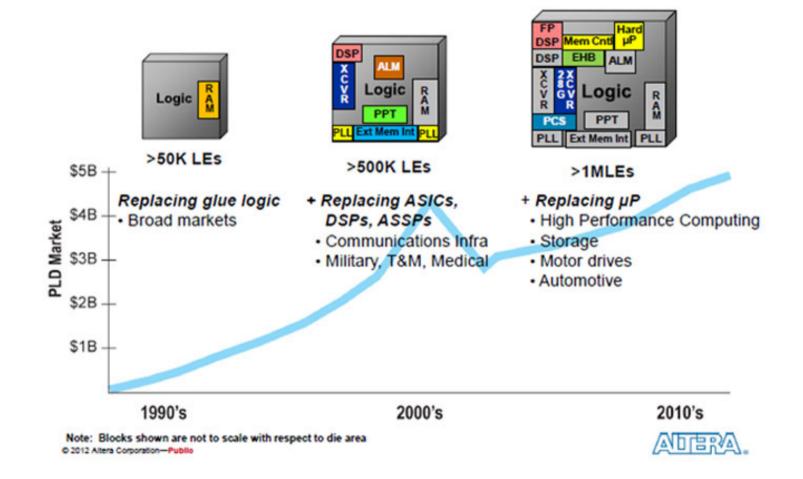
- SRAM
- Flash based
- Antifuse



Source: https://www.grandviewresearch.com/industry-analysis/fpga-market

FPGA Growth Trend

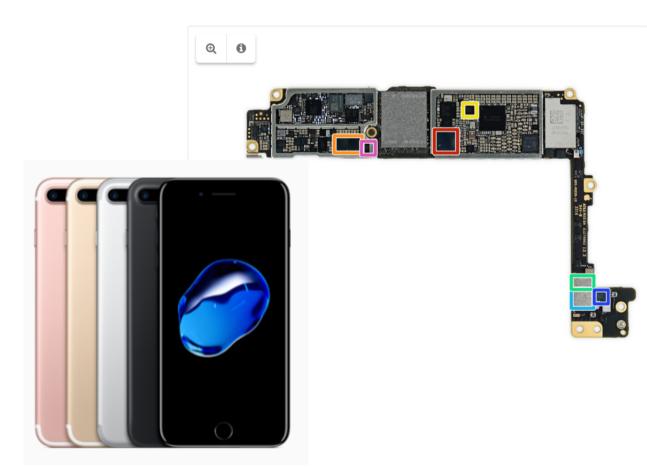
• 20 Years FPGAs have been swallowing up system components (by Altera, now a part of Intel)



Application Type Segments

- Industrial
- Automotive
- Consumer electronics
- Military & aerospace
- Telecom
- Data processing
- Others

iPhone7 Plus

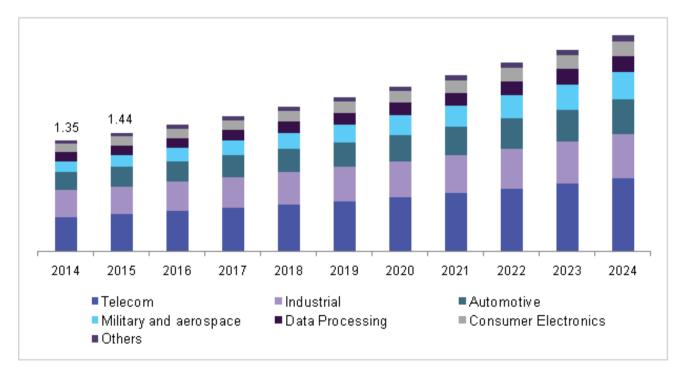


- But wait, there are even more ICs on the back!
 - Apple/Cirrus Logic 338S00105 Audio Codec
 - Cirrus Logic 338S00220 Audio Amplifier(x2)
 - Lattice Semiconductor ICE5LP4K
 - Skyworks 13702-20 Diversity Receive Module
 - Skyworks 13703-21 Diversity Receive Module
 - Avago LFI630 183439
 - NXP 610A38

Source: https://www.ifixit.com/Teardown/iPhone+7+Plus+Teardown/67384

Market by Application

U.S. FPGA Market by application, 2014 - 2024 (USD Billion)



Source: https://www.grandviewresearch.com/industry-analysis/fpga-market

Market Share by Vendor

	20	15		2016	
Vendor	FPGA Total	Market share	FPGA Total	Market share	Growth CY15-CY16
Xilinx	\$2,044	53%	\$2,167	53%	6%
Intel (Altera)	\$1,389	36%	\$1,486	36%	7%
Microsemi	\$301	8%	\$297	7%	-1%
Lattice	\$124	3%	\$144	3%	16%
QuickLogic	\$19	0%	\$11	0%	-40%
Others	\$2	0%	\$2	0%	0%
TOTAL	\$3,879	100%	\$4,112	100%	6%

Source EEtimes 3/5/2017

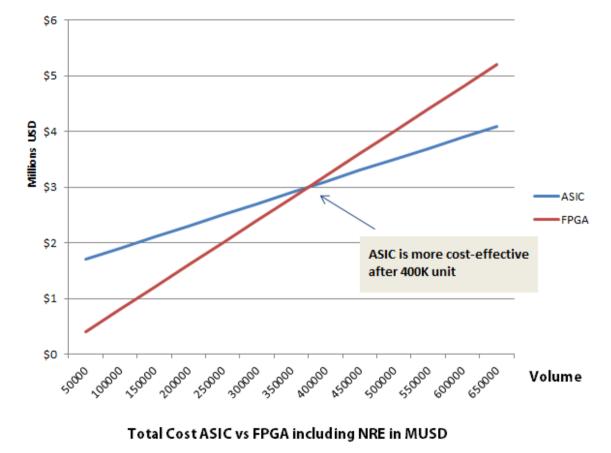
FPGA vs. ASIC: Which is Best?

anysilicon	FPGA	ASIC
Time to Market	Fast	Slow
NRE	Low	High
Design Flow	Simple	Complex
Unit Cost	High	Low
Performance	Medium	High
Power Consumption	High	Low
Unit Size	Medium	Low
	AnySilicon.com	_

Source: https://anysilicon.com/fpga-vs-asic-choose/

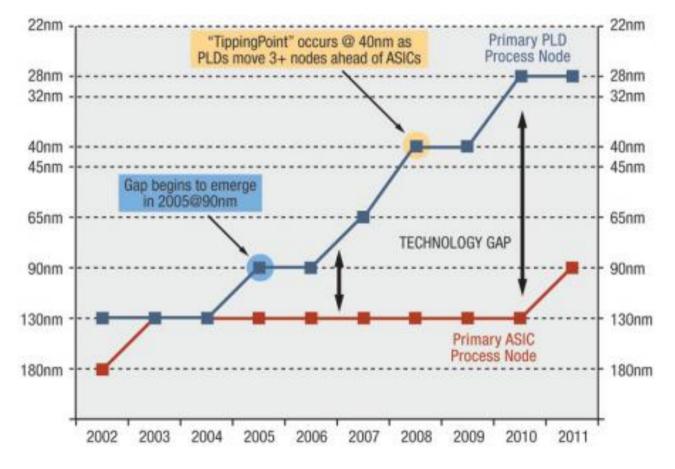
Price Comparison

- ASIC→NRE: \$1.5M, Unit cost: \$4
- FPGA→NRE: \$0, Unit cost: \$8



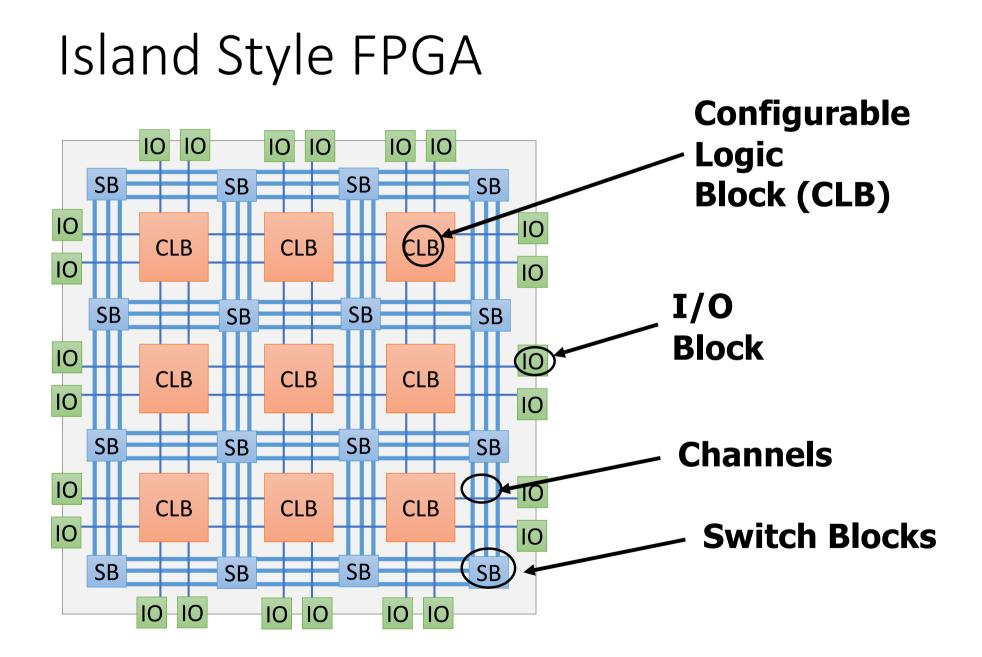
Performance Comparison

• The divergence between primary programmable logic device technology and that used for ASICs has continued to grow

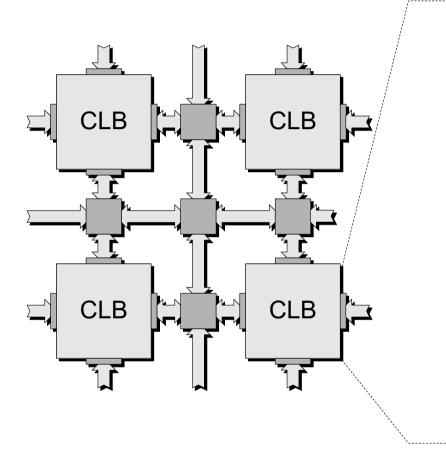


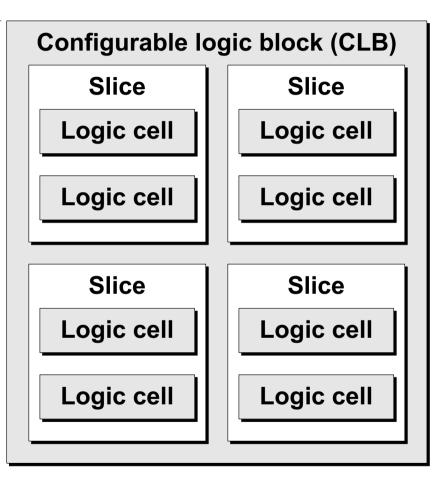
Source: http://archive.rtcmagazine.com/articles/view/102503

1.2 FPGA Architecture



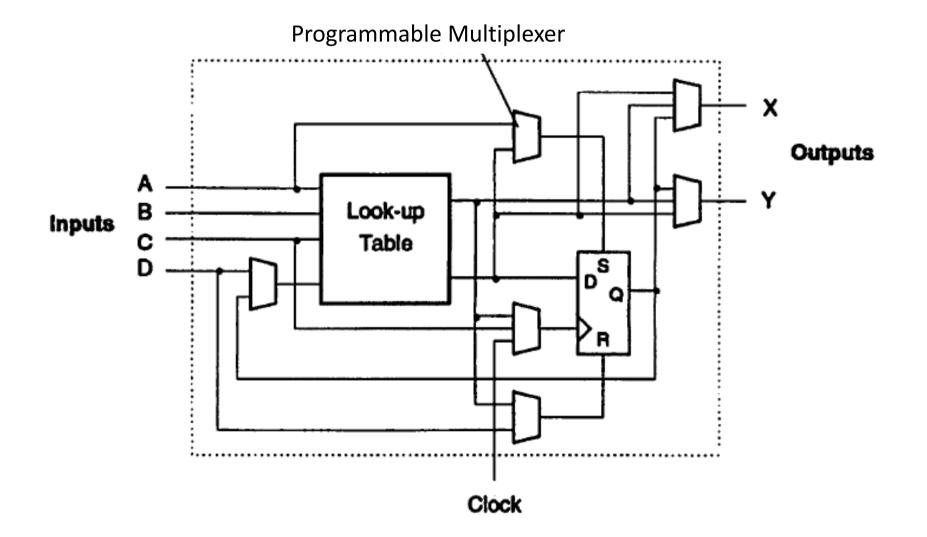
Xilinx CLB





The Design Warrior's Guide to FPGAs Devices, Tools, and Flows. ISBN 0750676043 Copyright © 2004 Mentor Graphics Corp. (www.mentor.com)

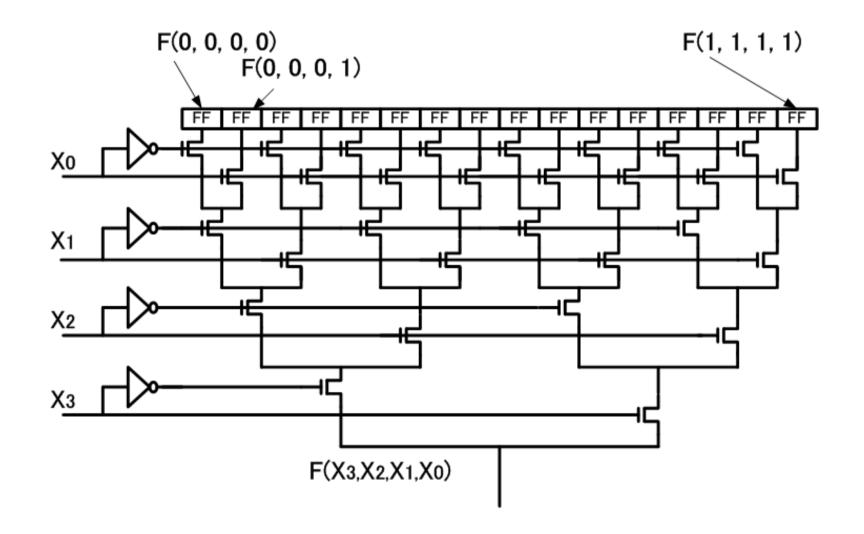
Logic Cell (Xilinx Inc. XC2000)

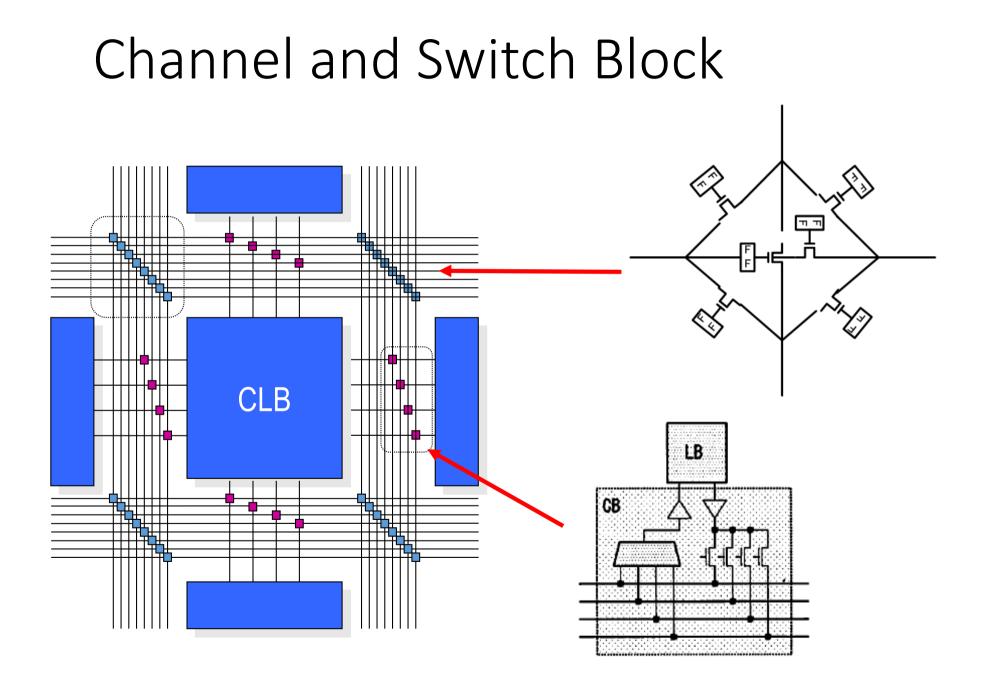


Realization of a Logic Function

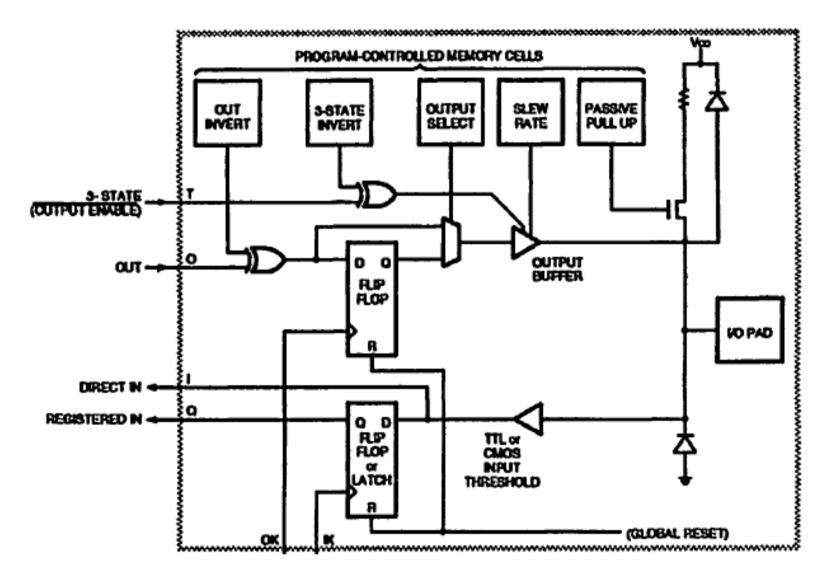
x0	x1	x2	У		x0	x1	x2	у
0	0	0	0		0	0	0	0
0	0	1	0		0	0	1	1
0	1	0	0		0	1	0	1
0	1	1	0		0	1	1	1
1	0	0	0		1	0	0	1
1	0	1	0		1	0	1	1
1	1	0	0		1	1	0	1
1	1	1	1		1	1	1	1

LUT Structure

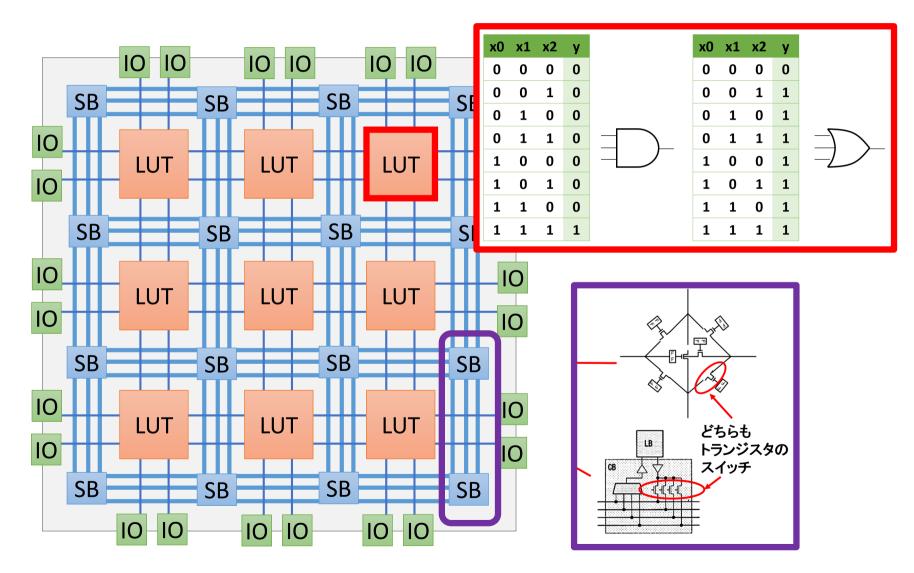




I/O Block

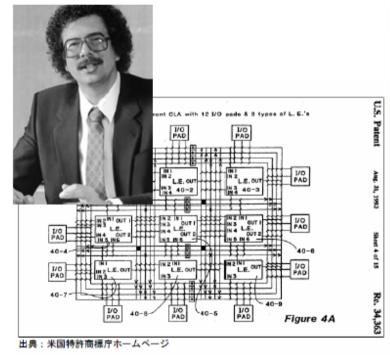


Memory-based realizes "programmable"

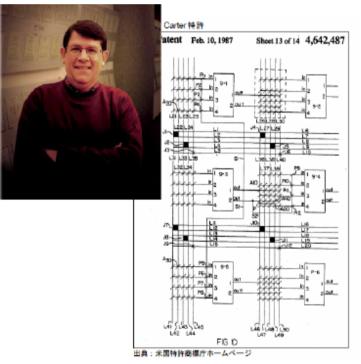


FPGA-world Famous Patents

US RE34363 by Ross H. Freeman Island style architecture

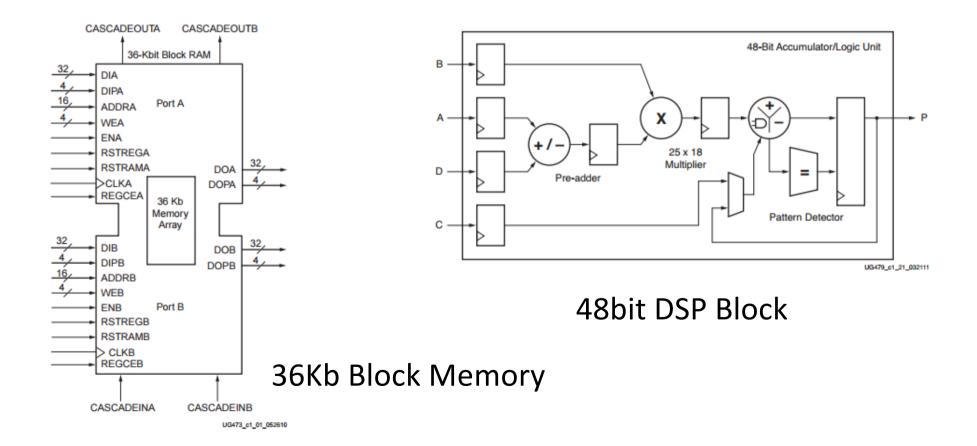


US 464248 by William S. Carter Connection architecture



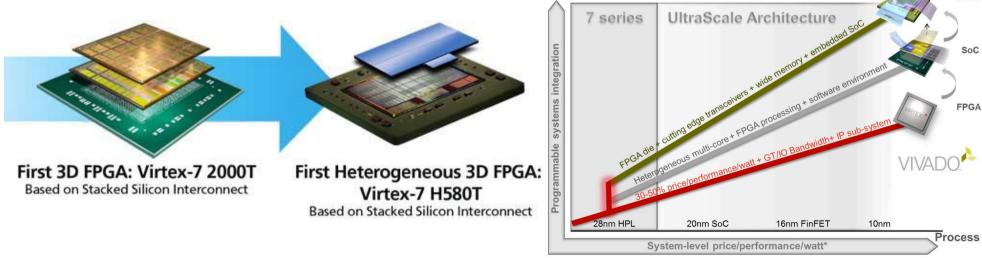
Hard macro (Dedicated Circuit)

• Standard IP cores are "Pre-built" in the FPGA



Xilinx FPGA Families

- 3D IC type
 - Virtex UltraScale+, Kintex UltraScle
- System on Chip (SoC) type
 - Zynq UltraSCale+
- Monolithic type
 - Artix(Low-cost), Spartan (Low-cost)

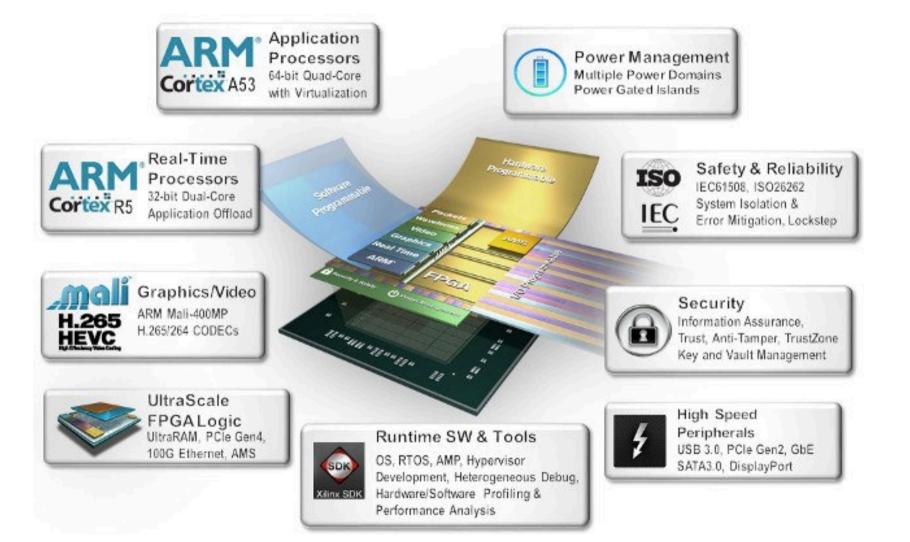


* System level combines unit with BOM cost

3D IC

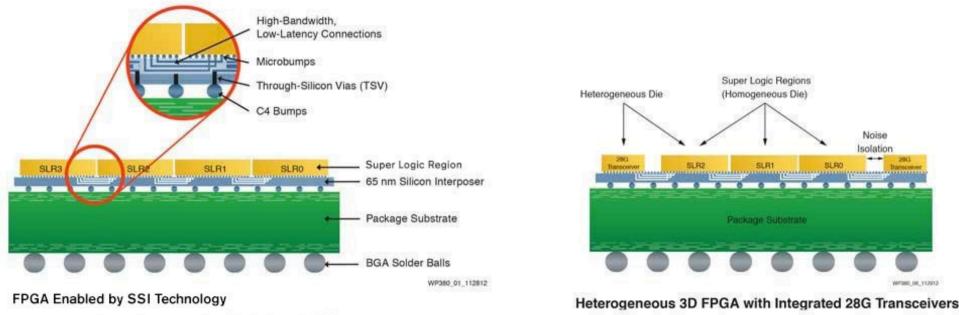
Source: http://www.xilinx.com

Xilinx Zynq Ultra Scale+



SSI(Stacked-Silicon Interconnect) Technology: Heterogeneous 3D FPGA

- High bandwidth connectivity across multiple dies
- Significantly increased die-to-die bandwidth per watt over multi-chip solutions
- Through-silicon via (TSV) with coarse pitch in passive silicon interposer (65nm) without transistor

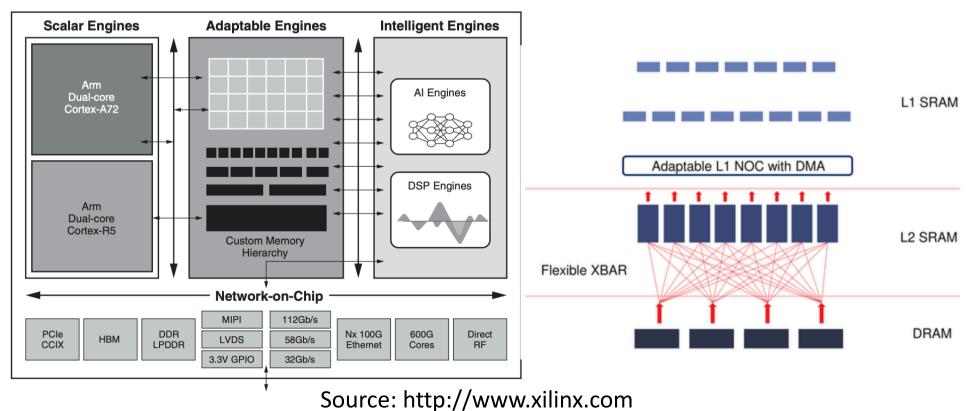


Source: http://www.xilinx.com

ACAP (Adaptive Compute Acceleration Platform)

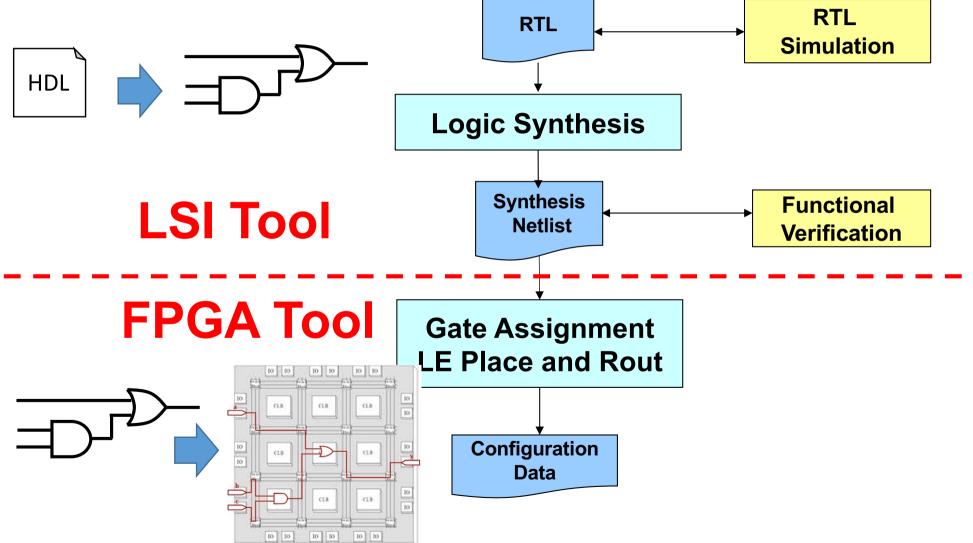


- VERAL AI core series and prime series
 - 7nm technology
- Connected 3 elements with high-band NoC and Memory

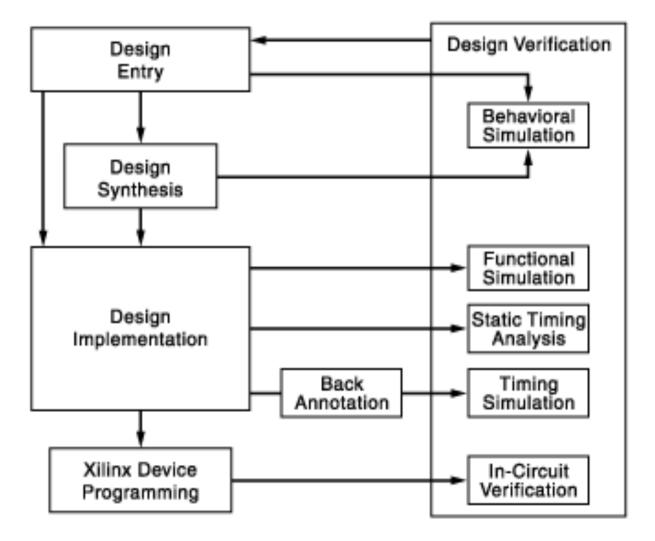


1.3 FPGA Design

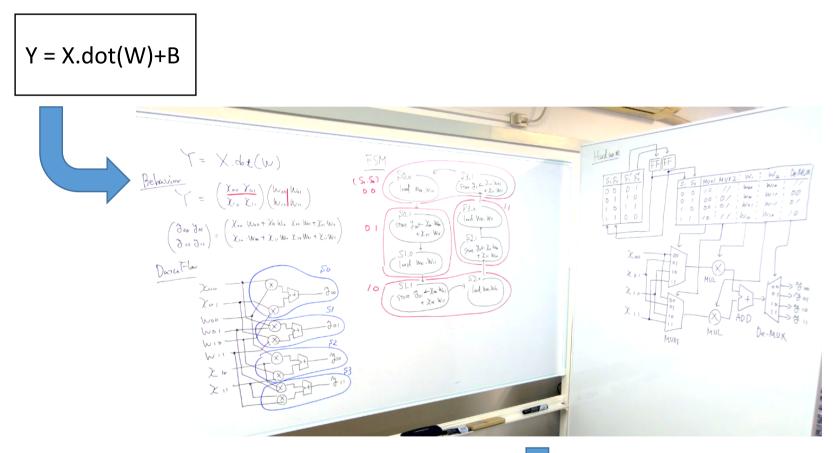
Standard FPGA Design



FPGA Design Flow



How to write a HDL?



Then, you can write your HDL!

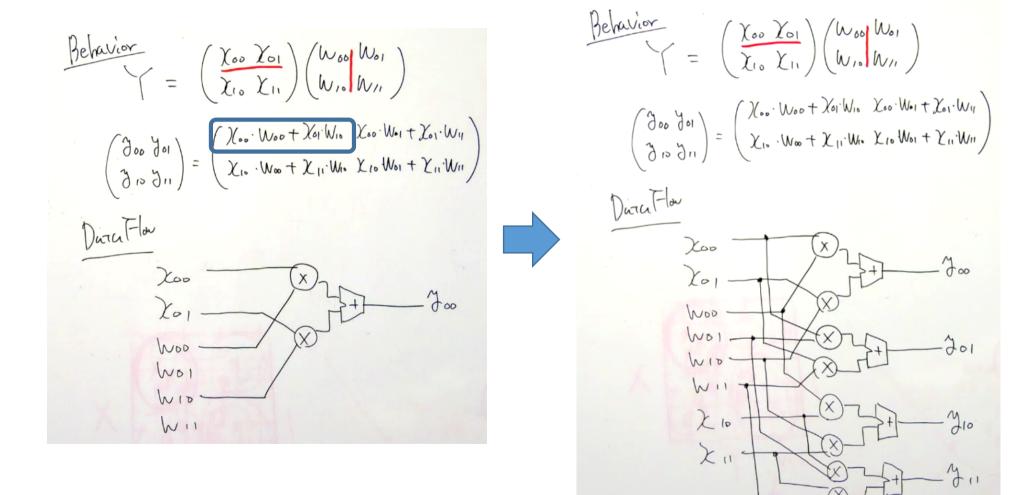
Matrix Multiplication

Y = X.dot(W) Behavior = (X00 Yo1) (W00 W01) (X10 X11) (W10 W11) $\begin{pmatrix} 3 & 0 & 0 \\ 3 & 0 & 0 \\ \end{pmatrix} = \begin{pmatrix} \chi_{00} \cdot W_{00} + \chi_{01} \cdot W_{10} & \chi_{00} \cdot W_{01} + \chi_{01} \cdot W_{11} \\ \chi_{10} \cdot W_{00} + \chi_{11} \cdot W_{10} & \chi_{10} \cdot W_{01} + \chi_{11} \cdot W_{11} \end{pmatrix}$

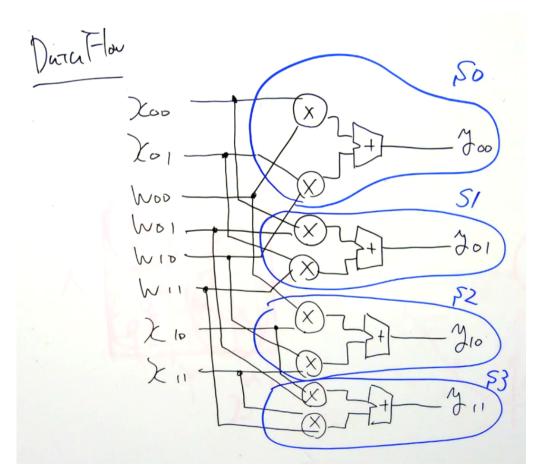
Alternatively, you can write a C-code

```
for(i=0;i<2;++i){
    for(j=0;j<2;++j){
        y[i][j] = x[i][j] * w[i][j];
        // Compute terms
        for(i=0;i<2;i++){
            for(j=0;j<2;j++){
                term = 0;
                for(k=0;k<2;k++)
                    term = term + x[i][k]*w[k][j];
                y[i][j] = term;
        }
    }
}</pre>
```

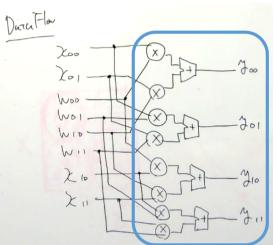
Data path description



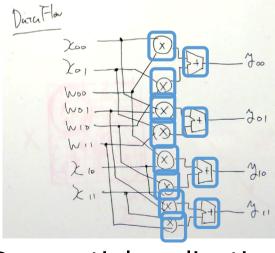
Scheduling



MACs (Multiply ACcumulations) realization

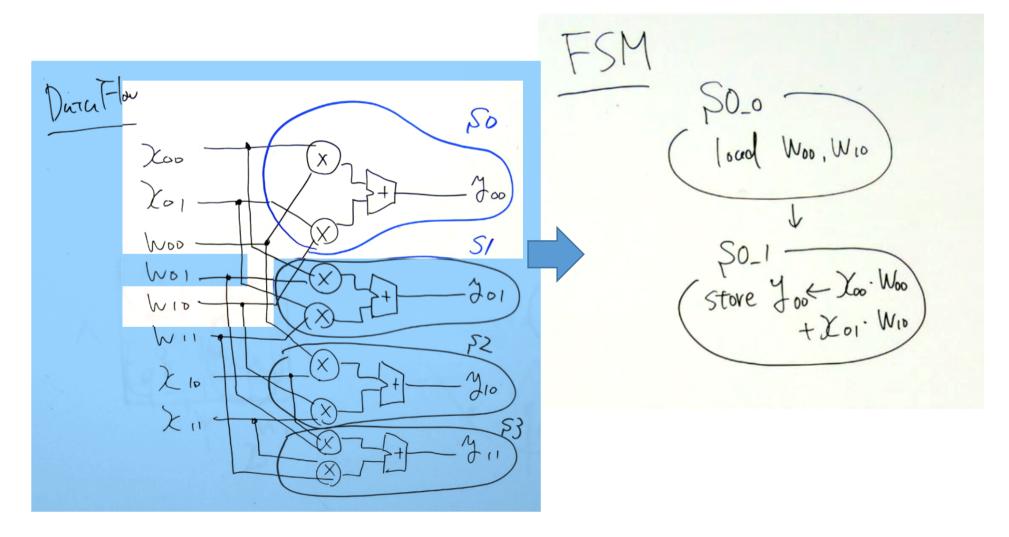


Fully parallel realization

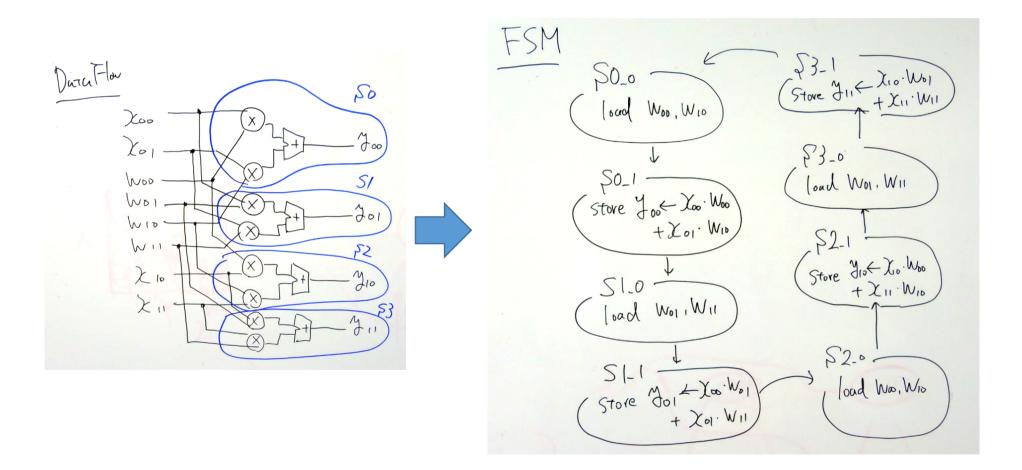


Sequential realization $_{37}$

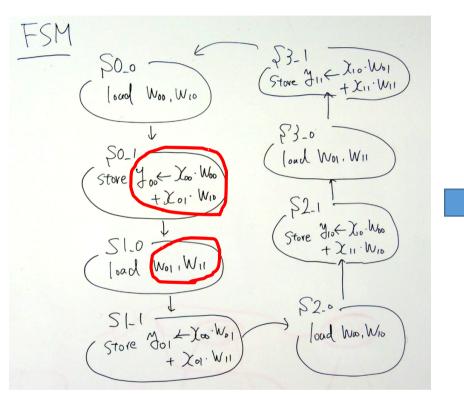
Finite State Machine (FSM)



FSM (Cont.)



FSM Optimization



Load weights during the MAC operation

Assign state variables (1-hot code, gray one, natural binary one)

Store You + Xor WII

23-

83-0

S2-

Store JIE X10-Wol

load Wor. WII

Store Yot Do. Woo

\$2.0

+ X11 W10

load Was, Wis

FSM

(5,.50)

DD

D

10

S0_0

000

SO_1

51.0

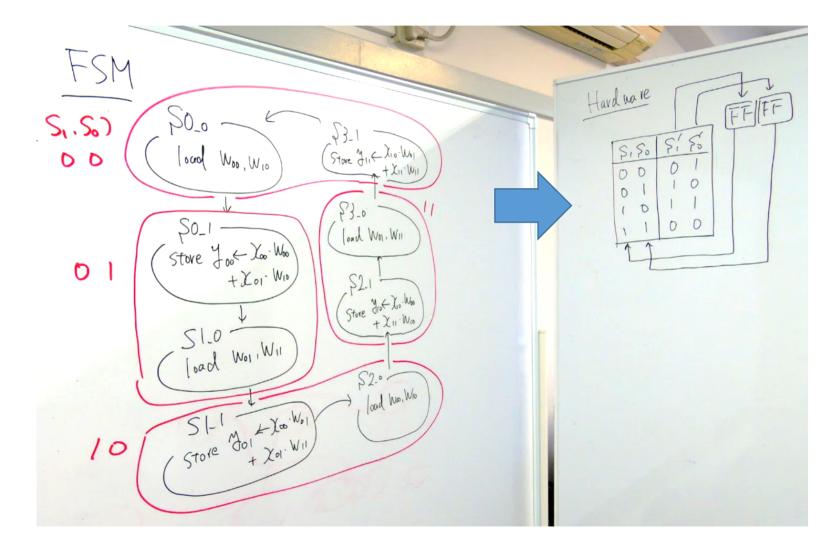
WOD, WIO

store you Xoo. Woo

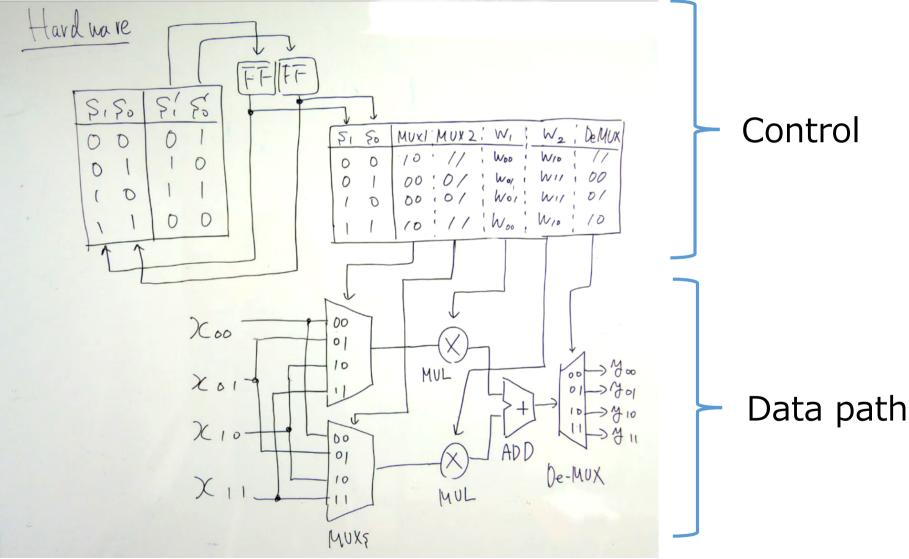
load Wor, Wil

+ Xol · Win

Realization of the FSM



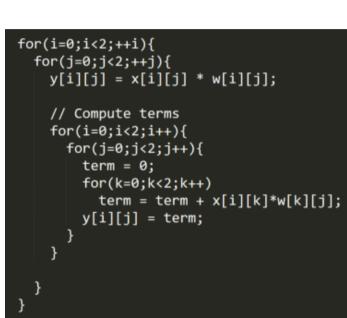
Assign to Primitives





Y = X.dot(W) + B

Python: single line!



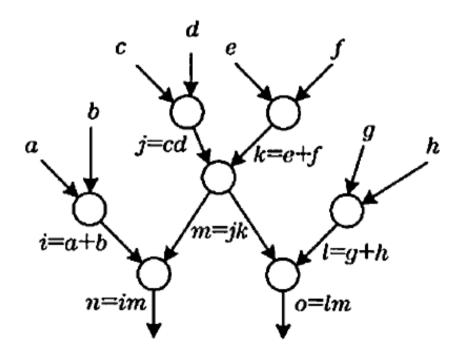
C/C++: ten lines

module mat_add(input clk, reset, input [7:0]x[0:3], output [7:0]y[0:3]): reg [1:0]state; reg [1:0]mux1, mux2; reg [7:0]w0, w1; reg [1:0]de_mux; always@(posedge clk or posedge rst)begin if(rst == 1'b1)begin state <= 2'b00 end else begin case(state) 2'b00:begin state <= 2'b01:</pre> mux1 <= 2'b10;</pre> mux2 <= 2'b11;</pre> w0 <= 8'b00101000; w1 <= 8'b11000101; de_mux <= 2'b11;</pre> end 2'b01:begin state <= 2'b10;</pre> mux1 <= 2'b00;</pre> mux2 <= 2'b01; w0 <= 8'b00101000; w1 <= 8'b11000101; de_mux <= 2'b00;</pre> end 2'b10:begin state <= 2'b11;</pre> mux1 <= 2'b00;</pre> mux2 <= 2'b01;</pre> w0 <= 8'b00101000; w1 <= 8'b11000101; de_mux <= 2'b01; end 2'b11:begin state <= 2'b00:</pre> mux1 <= 2'b00; mux2 <= 2'b01; w0 <= 8'b00101000; w1 <= 8'b11000101; de_mux <= 2'b10;</pre> end endcase end end wire [15:0]mul1, mul2; wire [16:0]w_add; assign mul1 = w0 * mux(mux1,x[0],x[1],x[2],x[3]); assign mul2 = w1 * mux(mux2,x[0],x[1],x[2],x[3]); assign w_add = mul1 + mul2; assign y[0] = (de_mux == 2'b00) ? w_add : 2'bzz; assign y[1] = (de_mux == 2'b01) ? w_add : 2'bzz; assign y[2] = (de_mux == 2'b10) ? w_add : 2'bzz; assign y[3] = (de_mux == 2'b11) ? w_add : 2'bzz; endmodule

Verilog-HDL: 66 lines

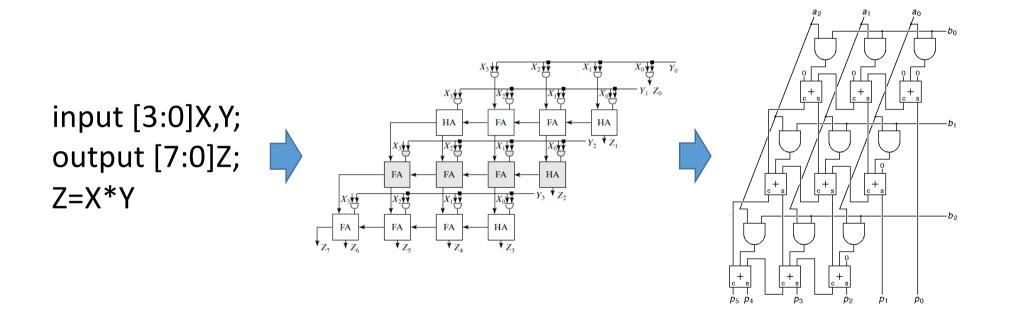
Boolean Network

- Representation of a combinational logic circuit using a directed graph without a cycle
- Vertex : Logic gate, Edge : Input or output



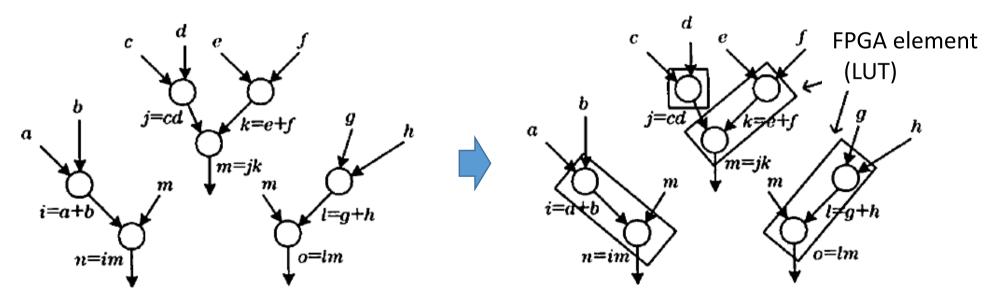
Logic Synthesis

• Synthesize from a given HDL specification to a Boolean network

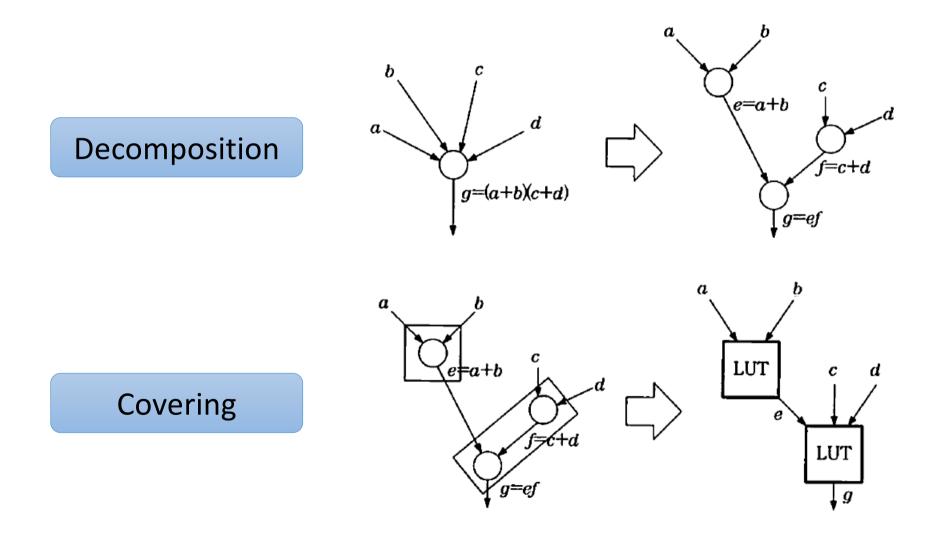


Technology Mapping

- A kind of a graph covering problem
- Goal: A depth optimized one by using a dynamic programming

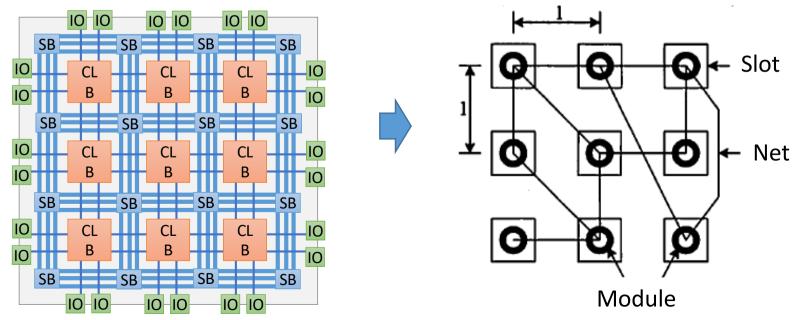


Decomposition and Covering



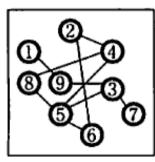
Placement

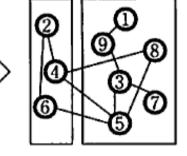
- Problem to place the module (logic gate) into the slot (location)
 - 2D allocation problem \rightarrow NP-complete
 - Approximation (Simulated annealing, or min-cut tech.)

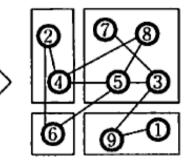


Min-cut Placement

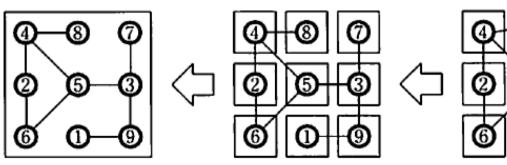
- Recursively divided a module set into two ones
 - Near-optimal solution can be obtained in the short time
- Used in a commercial FPGA design tool





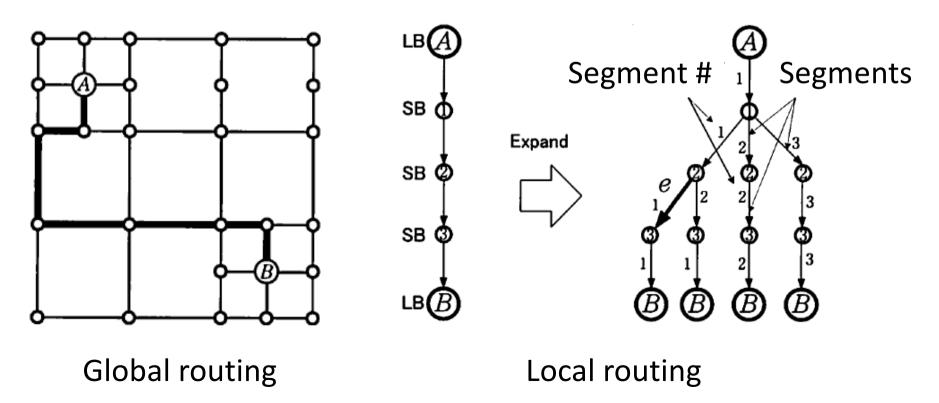




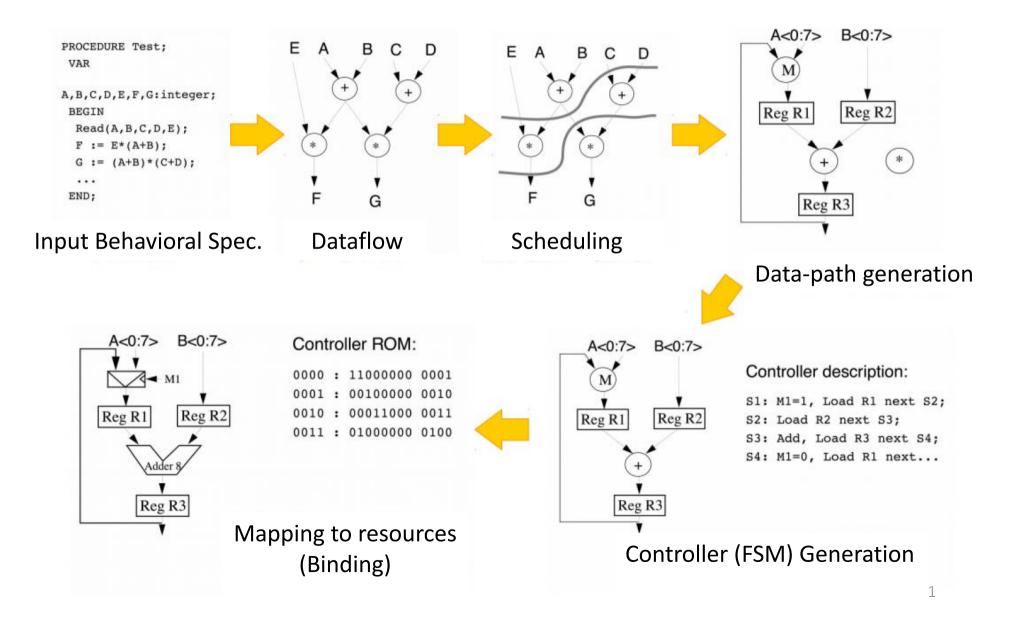


Routing

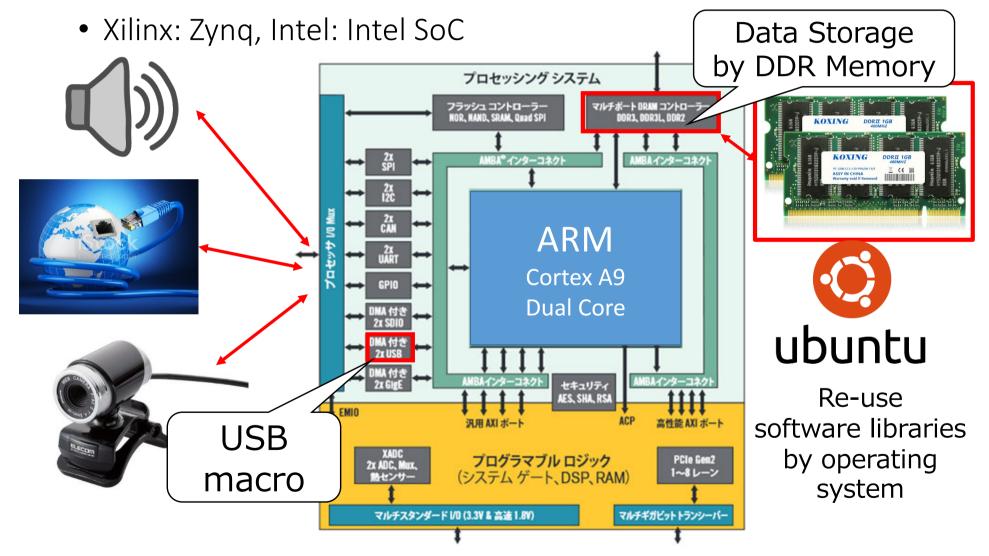
- Global routing: Determine the rough wiring path
- Local one: Determine the wiring segment and switch



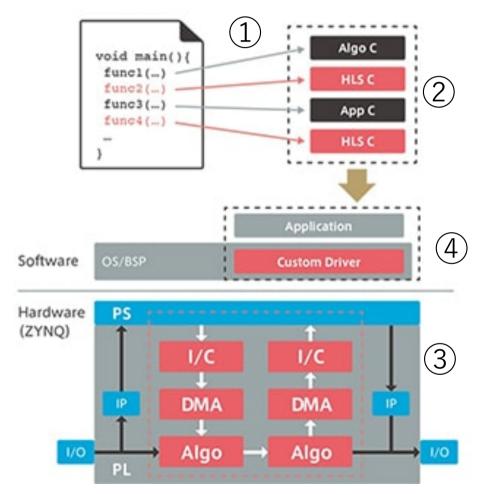
High-Level Synthesis (HLS)



System on Chip FPGA



Conventional Design Flow for the SoC FPGA

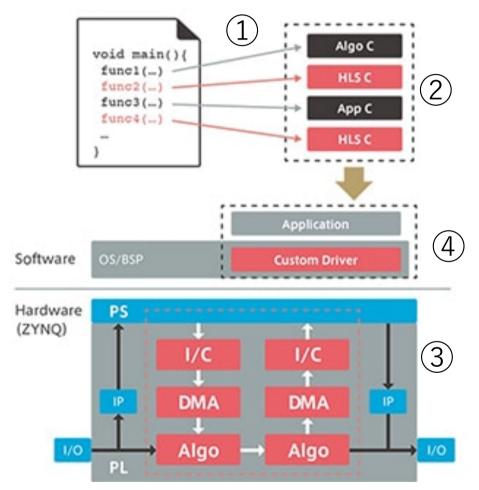


- 1. Behavior design
- 2. Profile analysis
- 3. IP core generation by HLS
- 4. Bitstream generation by

FPGA CAD tool

5. Middle ware generation

System Design Tool for the SoC FPGA

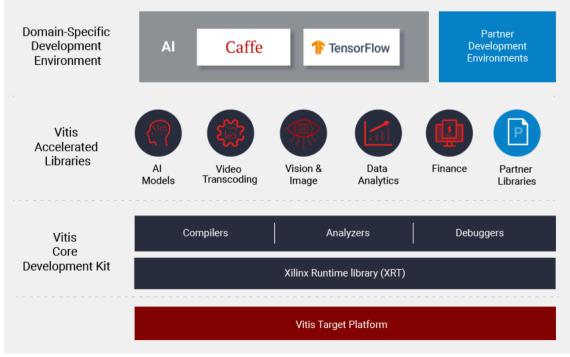


- 1. Behavior design
 - + pragmas
- 2. Profile analysis
- 3. IP core generation by HLS
- 4. Bitstream generation by FPGA CAD tool
- 5. Middle ware generation

Automatically done

Design Flow for Versal Architecture: e.g. Al Accelerator

- Application specific framework (Caffe, TensorFlow)
- Convert pre-trained model with Vitis Libraries
- Conventional system-design tool-flow



Source: Xilinx Inc.

Summary

- FPGA: Reconfigurable LSI or Programmable Hardware
- It consists of a programmable logic array and a programmable interconnection
- Standard FPGA design supports an RTL based one
- Benefits: Productivity, lower non-recurring engineering costs, maintainability, faster time to market

Homework 1

- 1. (Mandatory) Show an application using a FPGA
- 2. (Selective) The modern FPGA has several configuration devices as follows:
 - Static RAM (SRAM)
 - Flash memory
 - Anti-fuse

In that case, both the SRAM-based FPGA and Flash-based one supports "multiple-time" configurations, while an anti-fuse only "one-time" configuration. Actually, some vender adopts the antifuse-based FPGA than SRAM-based one. Why?

Deadline is 21st, Nov., 2019

(At the beginning of the next lecture)

Send a PDF file to nakahara{at}ict.e.titech.ac.jp